Composite Cryo-Detectors: Considerations on Thermo-Mechanical Stress

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Thermo-Mechanical Stress

CRESST – Light Yield as a mean of Discrimination



Detector physics define width of bands

No clear identification possible for event "C"

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CRESST – Light Yield as a mean of Discrimination



Narrower bands reduce overlap

Assignment more clear \rightarrow better discrimination, especially for low energies

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Production Steps

Scintillating crystal



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- Scintillating crystal
- Thin film evaporation



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Problem

- High temperatures needed for evaporation
- Oxygen depletion
- Up to 50 % degradation of light output

Improving Light via Composite Technique





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Glue a small thermometer carrier onto a big target crystal

- Improves the light output
- Simplifies production



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My work: Investigate gluing technique

- Does it improve the detector?
- Discrimination of carrier-events?
- Are there other unwanted effects?



Thermo-mechanical issue: Glue vs. Crystal



2 materials cooled down: \Rightarrow thermo-mechanical stress

• Destruction of the detectors

• Might fake D.M. events

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FEM simulation

- Thickness of the glue layer
- Diameter of the glue layer
- Orientation of the two crystals

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Results:

- Thin (\leq 40 μ m) layer is crucial
- Diameter and crystal orientation are not very important

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- Main stress (possible cracks) occurring at the edge
- ullet \Rightarrow Significant part of the phonons headed towards carrier

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- Main stress (possible cracks) occurring at the edge
- ullet \Rightarrow Significant part of the phonons headed towards carrier
- Events involving the carrier have a different signal shape
- All carrier like events in Dark Matter data have light
- ullet \Rightarrow The glue does not fake Dark Matter signals

- Light signal crucial for event discrimination
- Composite technique improves light signal
- Thin glue layer avoids cracks
- Glue does not introduce fake Dark Matter signals

The mandatory ATLAS Picture



Thank you for your attention

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